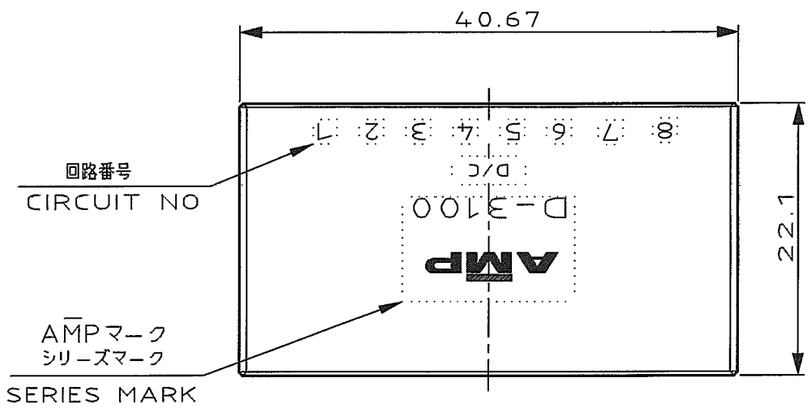
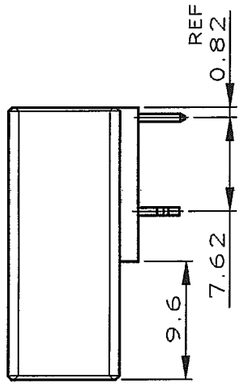
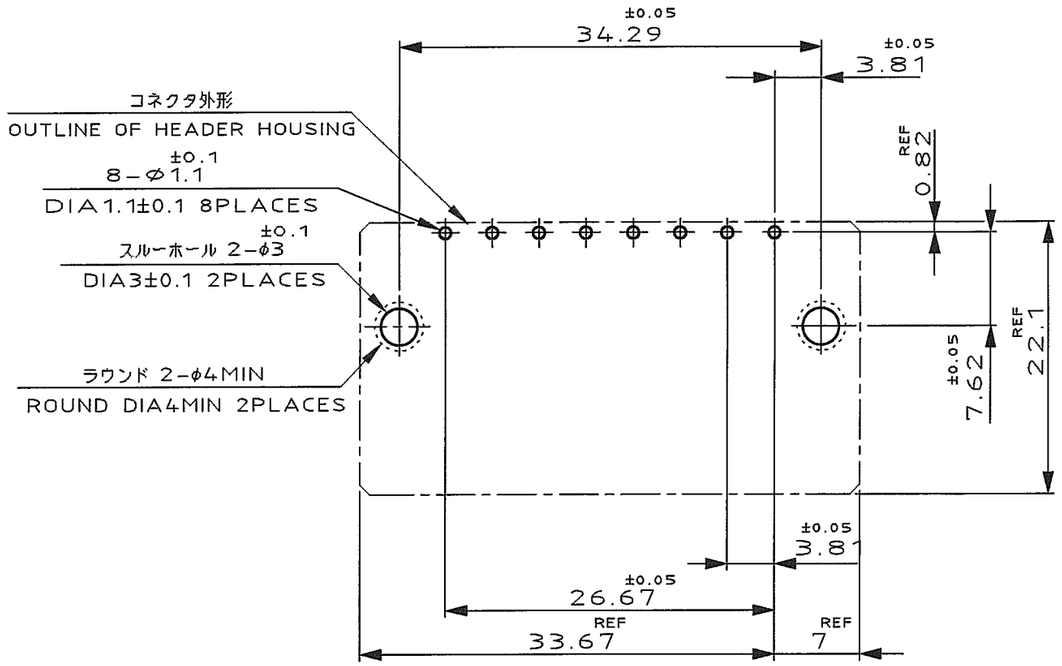
NUMBER 178297

3rd ANGLE PROJECTION

METRIC





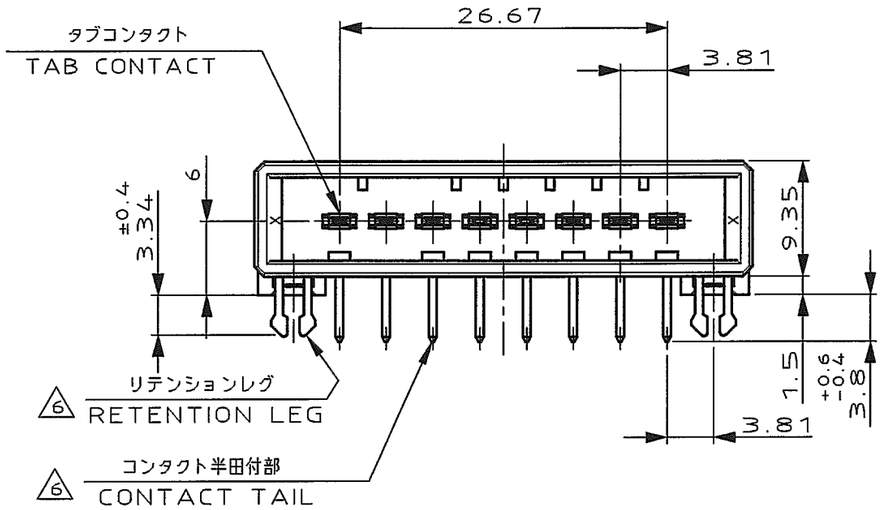


推奨基板取付け穴寸法

PC 基板厚：1.6±0.1
（非累積公差）
（コネクタ搭載面）

RECOMEND PC BOARD HOLE PATTERN

PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)



NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY

2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING

3. FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING

4. FINISH(CONTACT AREA):2.0 μmMIN TIN PLATED OVER NICKEL

~~5. FINISH(RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL~~

6. FINISH(RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注 記

1. 材料：ハウジング：ガラス入り熱可塑性ポリエステル樹脂
コンタクト：銅合金
リテンションレグ：銅合金

2. めっき：コンタクト：全面Ni下地
接触部：0.38μm MIN金めっき

3. めっき：コンタクト：全面Ni下地
接触部：0.76μm MIN金めっき

4. めっき：コンタクト：全面Ni下地
接触部：2.0 μm MINスズめっき

~~5. めっき：リテンションレグとコンタクト半田付部：ニッケル下地の上に半田めっき~~

6. めっき：リテンションレグとコンタクト半田付部
：ニッケル下地の上にスズめっき

6	4	1-178297-5
6	3	1-178297-3
6	2	1-178297-2
(FINISH)		製品番号 (PART NO.)

LTR	REVISION RECORD	DR	CHK	DATE
B	REVISED(FJD0-0039-03)	TS	S.A	6/3 '03
A	REVISED(FJD0-0114-03)	TS	SM	25.APR '03
0	PROPOSED	NM	H.O / S.M	7-1 '91

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tyco Electronics — Tyco Electoronics AMP K.K Kawasaki,Japan

WIRE RANGE	mm²(AWG -)
INSULATION DIA	- mmφ
MATERIAL	SEE NOTE 注記参照
FINISH	SEE NOTE 注記参照
DR.	N.Matsubara 14 JUN 91
DE.	N.Matsubara 14 JUN 91
CHK.	M.Obata 1 JUL '91
APP.	S.MANABE 1-JUL-'91

NAME: 8 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100

一般公差 (GENERAL TOLERANCE): 10以下 ±0.3; 10を超え30以下 ±0.4; 30を超え100以下 ±0.5; 角度 ±3°

SIZE	LOC	NUMBER	SCALE	REV.	SHEET
A3	J	C-178297	2-1	B	1 OF 1

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

AMP-J REV.10/'83

(CUSTOMER DRAWING) 顧客用図面